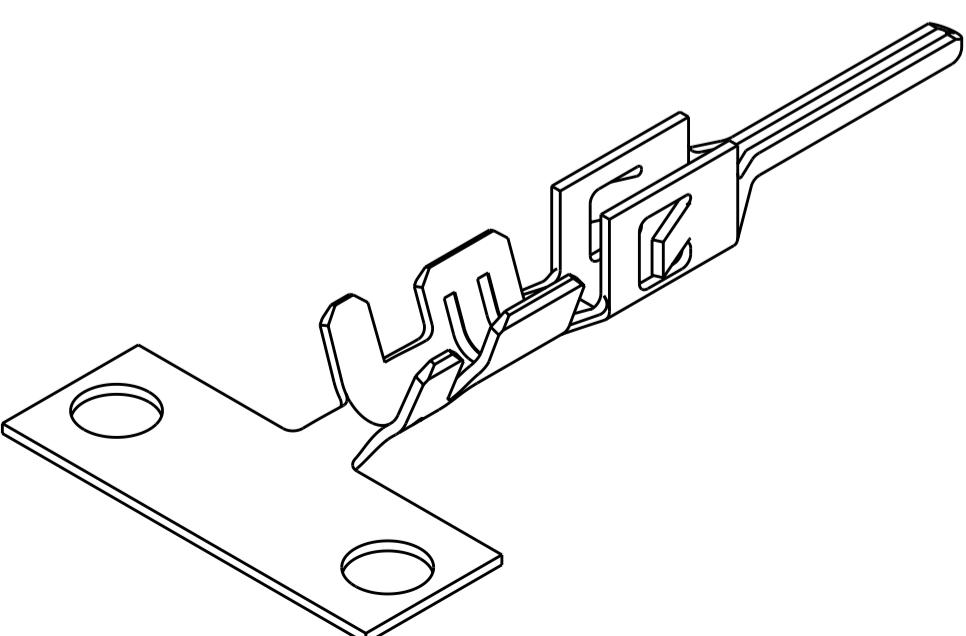
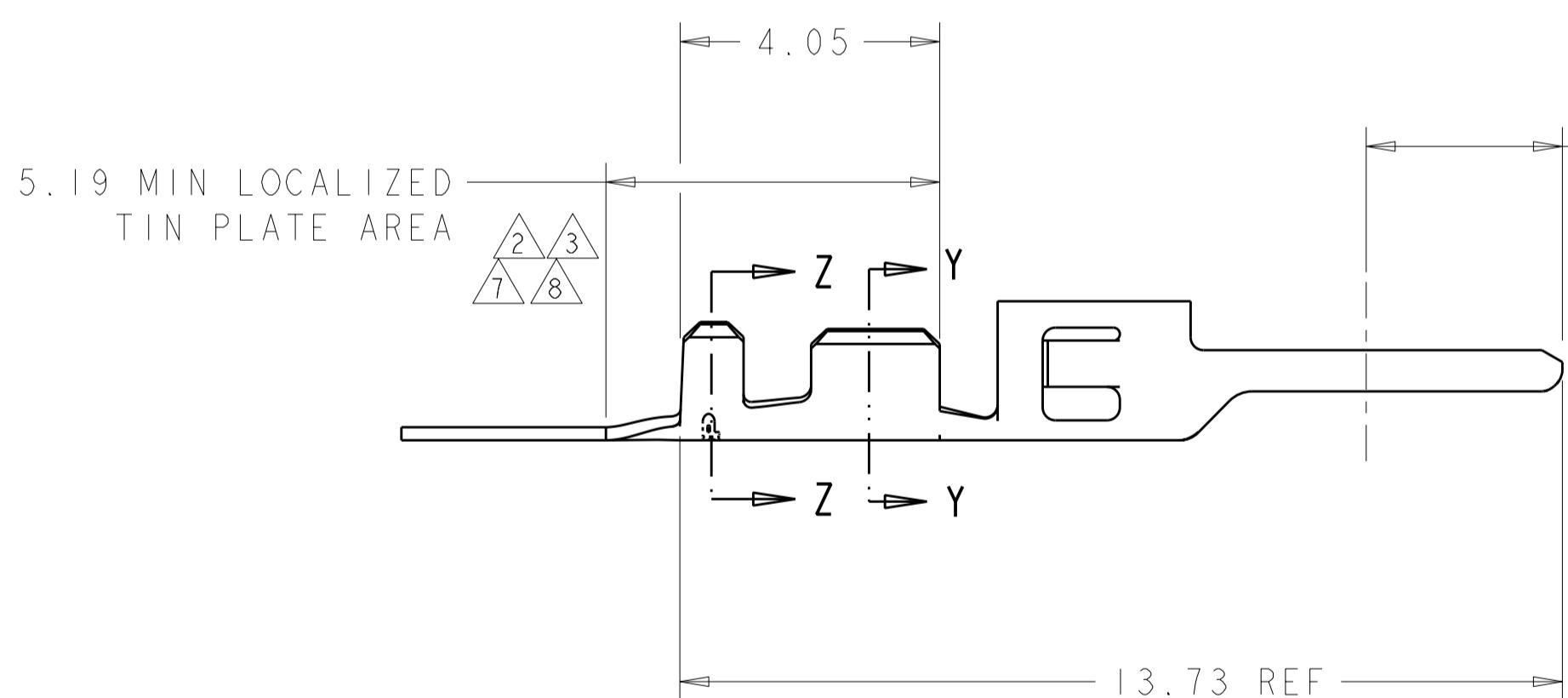
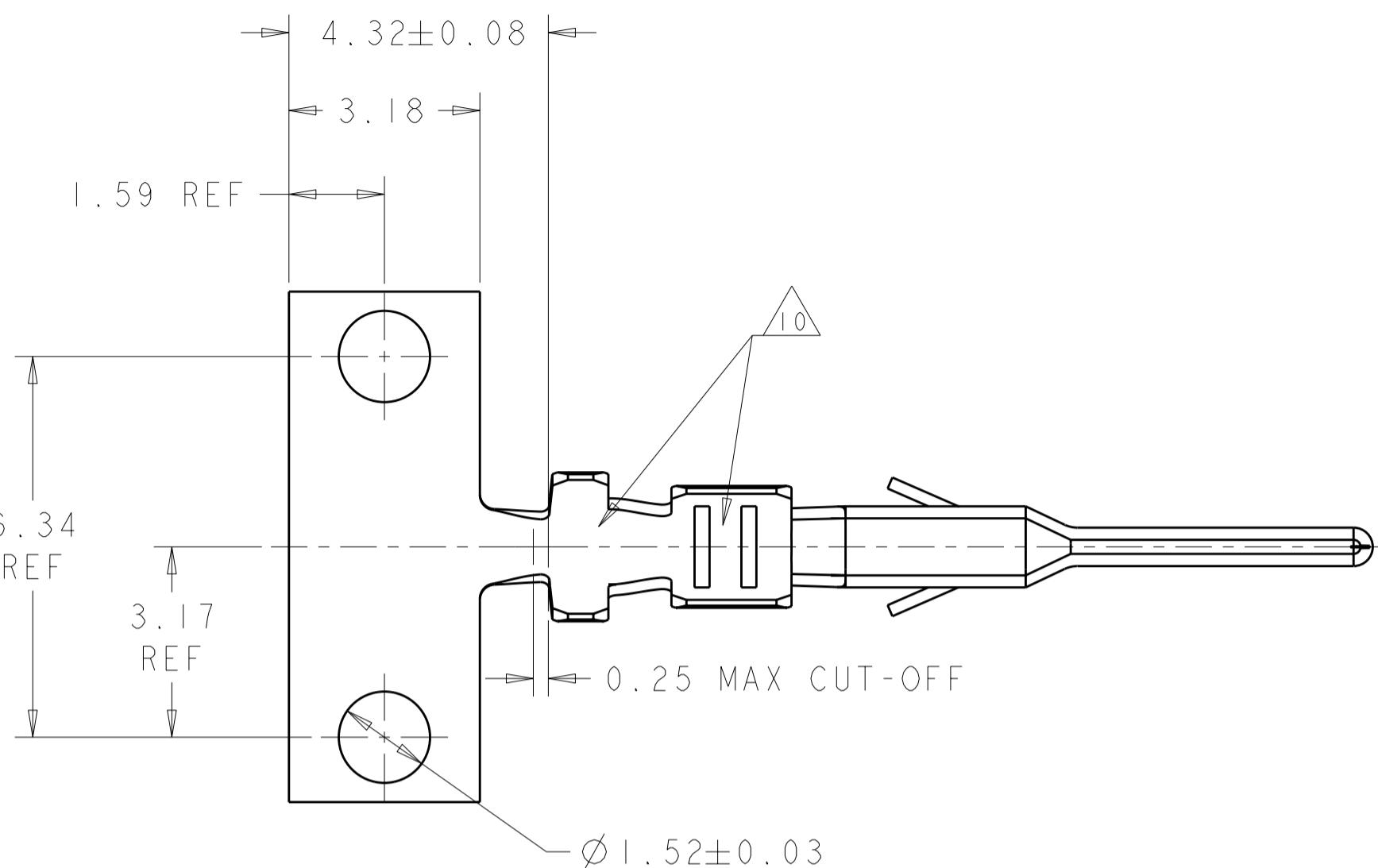


THIS DRAWING IS UNPUBLISHED.
RELEASED FOR PUBLICATION 20
BY -
ALL RIGHTS RESERVED.

© COPYRIGHT 20 BY -

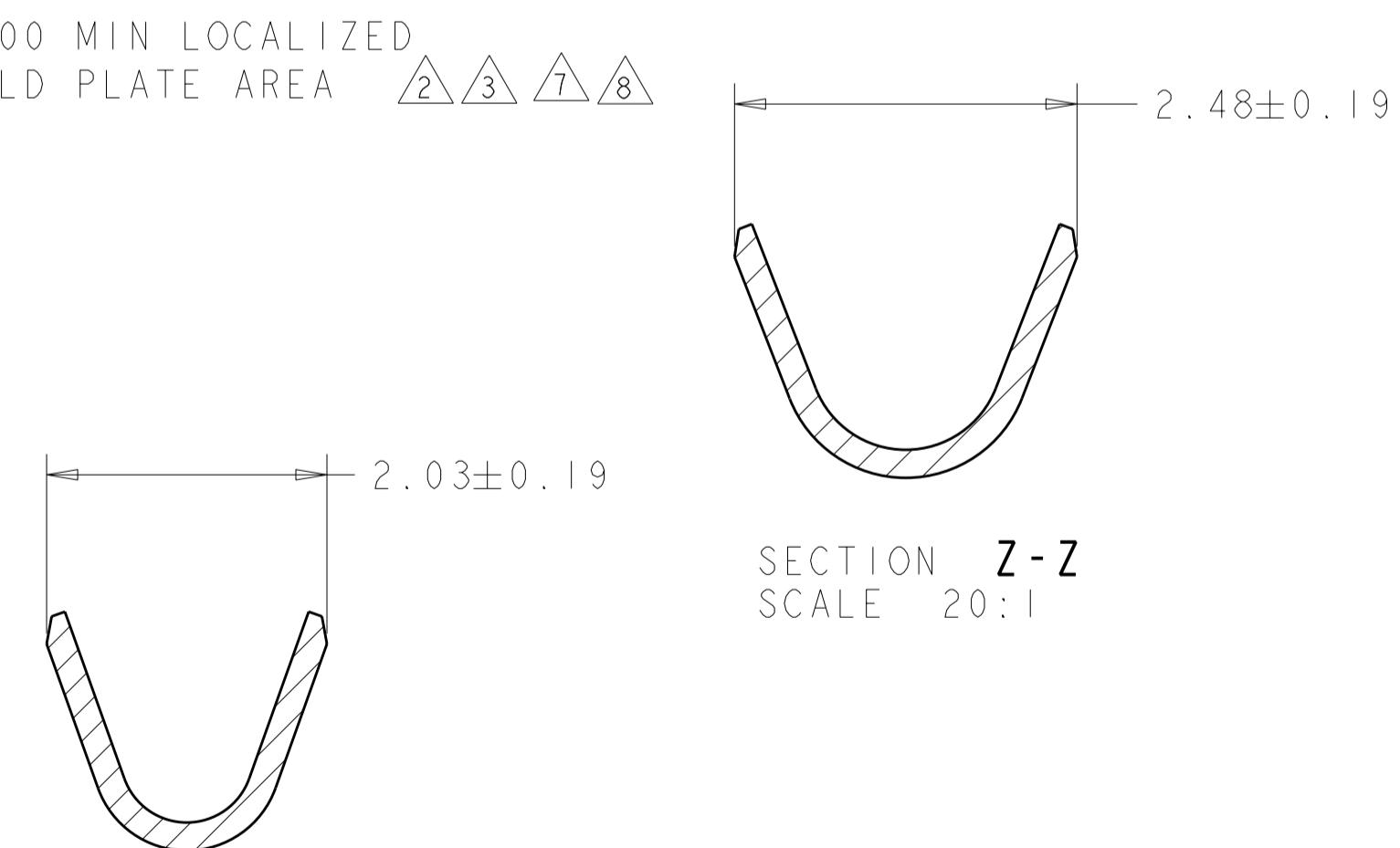
LOC			DIST		REVISIONS			
CM	00	P	LTR	DESCRIPTION	DATE	OWN	APVD	
		D2		REVISED PER ECO-11-005027	15MAR2011	RK	HMR	



SECTION Y-Y
SCALE 20:1

METRIC

- 1 2.54 μm MIN BRIGHT TIN/LEAD ENTIRE STOCK OVER 1.27 μm MIN NICKEL ENTIRE STOCK.
- 2 0.38 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 μm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27 μm MIN NICKEL ON ENTIRE STOCK.
- 3 0.76 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 μm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27 μm MIN NICKEL ON ENTIRE STOCK.
- 4. WIRE RANGE 20-24 AWG.
- 5. INSULATION RANGE 0.89-1.52
- 6 2.54 μm MIN BRIGHT TIN ENTIRE STOCK OVER 1.27 μm MIN NICKEL ENTIRE STOCK.
- 7 0.38 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 μm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27 μm MIN NICKEL ON ENTIRE STOCK.
- 8 0.76 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 μm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27 μm MIN NICKEL ON ENTIRE STOCK.
- 9 NOTE DELETED.
- 10 TIN PLATING THICKNESS INSIDE WIRE AND INSULATION BARRELS TO BE 1.27 μm MIN.



SECTION Z-Z
SCALE 20:1

8	I - 794608 - 2
7	I - 794608 - 1
6	I - 794608 - 0
3	794608 - 3
2	794608 - 2
1	794608 - 1
FINISH	

PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN W J RUDY 29AUG2000	TE Connectivity
DIMENSIONS: mm		CHK W DAVIS 29AUG2000	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC \pm 1 PLC \pm 2 PLC \pm 3 PLC \pm 4 PLC \pm ANGLES \pm		APVD W DAVIS 29AUG2000	
0.20 THK BRASS	FINISH	PRODUCT SPEC - APPLICATION SPEC - WEIGHT -	NAME PLUG CONTACT, CRIMP SNAP, 20-24 AWG, MICRO MATE-N-LOK(TM)
		MATERIAL 0.20 THK BRASS	SIZE CAGE CODE DRAWING NO A2 00779 C-794608
			RESTRICTED TO -
			CUSTOMER DRAWING

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[1-794608-0](#)